ABSTRACT OF THE DISCLOSURE

The resin-encapsulated semiconductor device of the present invention includes: a die pad provided by thinning a lower portion of a lead frame; a semiconductor chip mounted on the die pad; a plurality of leads provided by thinning an upper portion of the lead frame; a connection member for connecting the semiconductor chip and the lead with each other; a plurality of suspension leads connected to the die pad; and an encapsulation resin for encapsulating an upper portion of the lead frame. In this way, it is possible to further reduce the thickness of a resin-encapsulated semiconductor device, while upsetting the die pad. Furthermore, the stress occurring from the encapsulation resin is absorbed by the self flexural deformation of the die pad and the lead, which are thinned, thereby improving the connection reliability.